



ALLIANCE MEMORY MDS REPORT

Part Description:		AS4C32M8D1-5TCN / AS4C32M8D1-5TIN							
Wieght (mg):		553.930 mg							
No.	Part Name	Material Name	Material mass (mg)	Substance in Materials	CAS Number	Element wt (%)	Element wt (mg)	wt % of total unit wt	PPM
1	Chip	Silicon	6.734	Silicon (Si)	7440-21-3	100.00%	6.734	1.216%	1000000
2	Leadframe	Metal	176.216	Iron	7439-89-6	57.450%	101.236	18.276%	574500
				Manganese	7439-96-5	0.800%	1.410	0.254%	8000
				Nickel	7440-02-0	41.000%	72.249	13.043%	410000
				Chormium	7440-47-3	0.250%	0.441	0.080%	2500
				Cobalt	7440-48-4	0.500%	0.881	0.159%	5000
3	Mold compound	Epoxy	366.6529	Epoxy Resin	Trade secret	4.0%	14.666	2.648%	40000
				Phenol Resin	Trade secret	4.0%	14.666	2.648%	40000
				Metal hydroxide	Trade secret	4.0%	14.666	2.648%	40000
				Carbon black	1333-86-4	0.2%	0.733	0.132%	2000
				Silica	60676-86-0	86.8%	318.255	57.454%	868000
				Others	Trade secret	1.0%	3.667	0.662%	10000
4	Epoxy/Die Adhesive	Plastic/Epoxy	1.01	Acrylic resin	Trade secret	6.00%	0.061	0.011%	60000
				Polybutadiene derivative	Trade secret	6.00%	0.061	0.011%	60000
				Butadiene derivative	Trade secret	2.00%	0.020	0.004%	20000
				Acrylate	Trade secret	4.00%	0.040	0.007%	40000
				Epoxy resin	Trade secret	2.00%	0.020	0.004%	20000
				Peroxide	Trade secret	1.00%	0.010	0.002%	10000
				Additive	Trade secret	2.00%	0.020	0.004%	20000
				Silver	7440-22-4	77.00%	0.779	0.141%	770000
5	Plating Solder ball	Resin	2.4795	Solder	7440-31-5	99.99%	2.479	0.448%	999900
				Lead	7439-92-1	0.01%	0.000	0.000%	100
6	Gold Wire	Metal	0.836	Gold	7440-57-5	99.99%	0.836	0.151%	999900
				Others	Trade secret	0.01%	0.000	0.000%	100